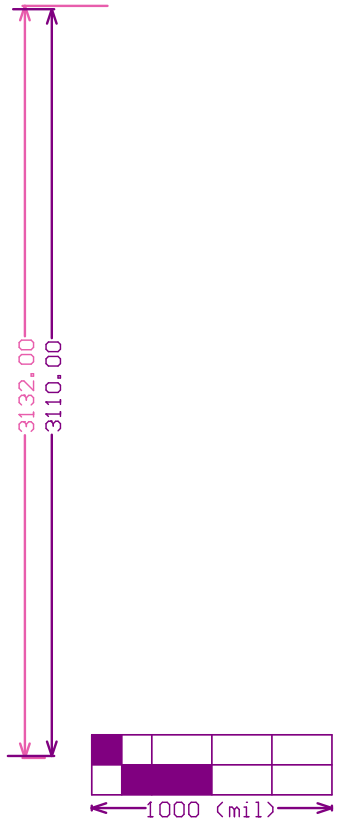
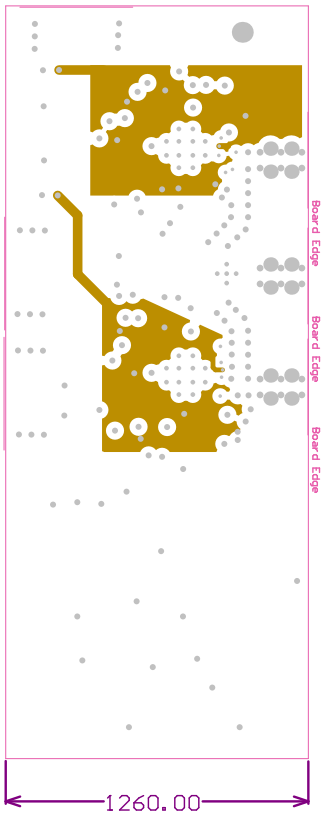
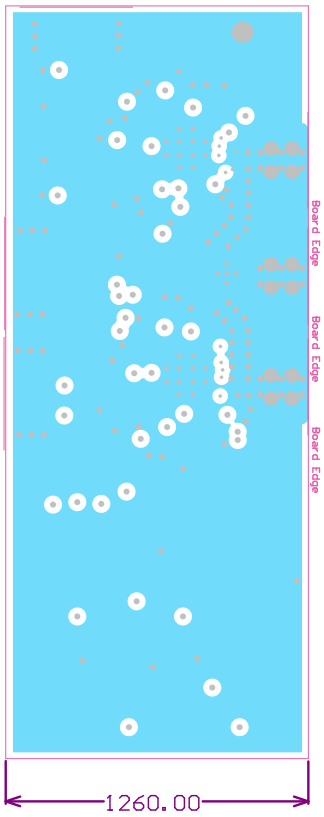


M2p Board Dimensions



M2 Board Dimensions



M2 Board Dimensions

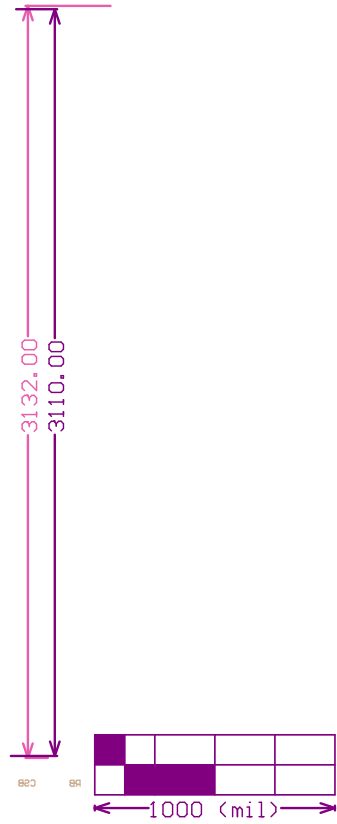
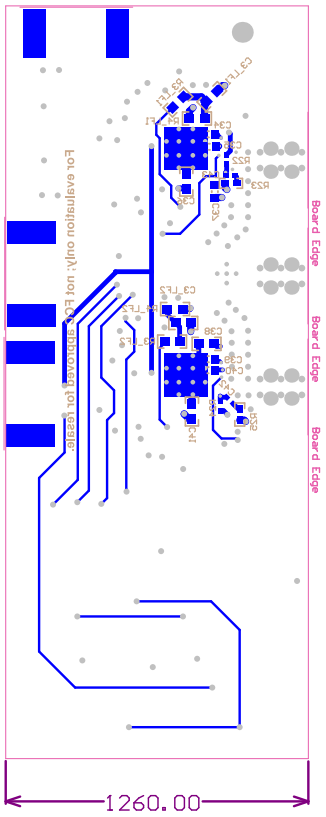
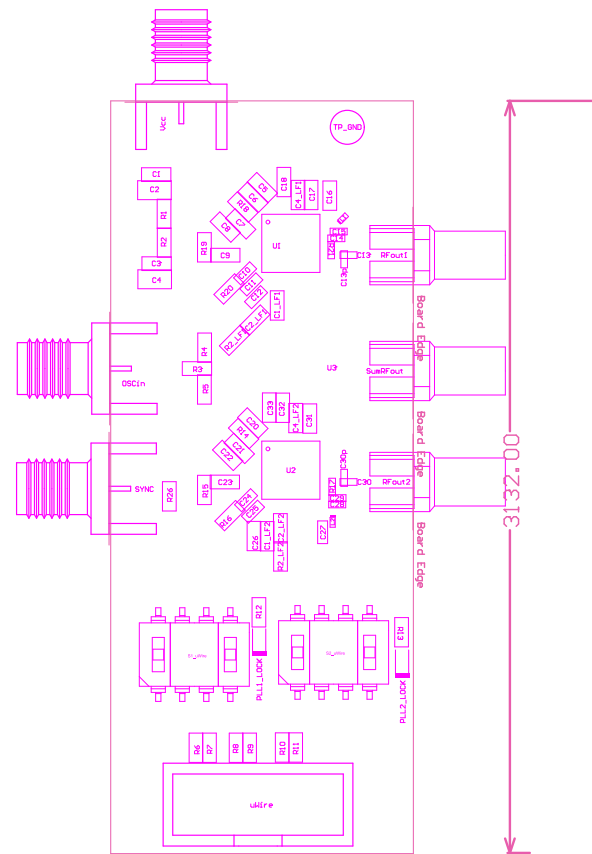


Fig 2. Board Dimensions

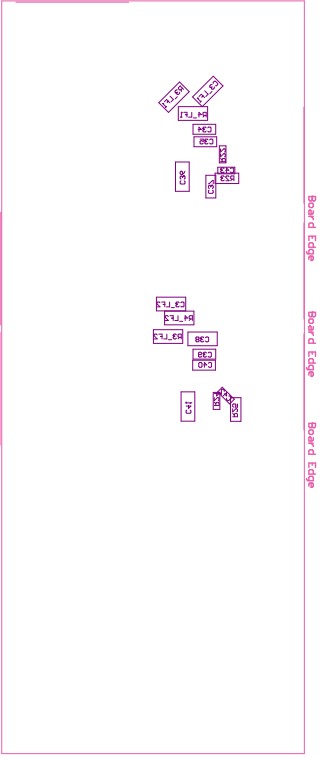


COMPONENTS PARKED 'DNP' SHOULD NOT BE POPULATED.

ASSEMBLY VARIANT

{No Variations}

| | | | | | | |
|--------------------------|----------------------|------------|----------|------------|-------------------|-----------------------|
| PCB VIEWED FROM TOP SIDE | BOARD #: | TIDA-01410 | REV: | A | SUN REV: | Not In VersionControl |
| M1 Board Outline | | TID #: | .TID | | | |
| PLOT NAME = | Top Assembly Diagram | GENERATED: | 4/6/2017 | 6:17:39 PM | TEXAS INSTRUMENTS | |



| | | | | | | | |
|---------------------------|-----------|-------------|-------------------------|------------|------------|------------|--------------------|
| PCB NEED FROM BOTTOM BLOB | BOARD # | 01P-10-ADIT | REV | A | REV | 2018 08/28 | Not In Use/Control |
| PLT INK = 3000 | LTID # | 011 | M1 Board Outline | | | | |
| Bottom Assembly Drawn | GENERATED | 1 | 11/15/2017 | 11/15/2017 | 11/15/2017 | 11/15/2017 | TEKINS INSTRUMENTS |

ASSEMBLY INSTRUCTIONS
THIS VERSION

COMPONENTS MARKED 'DPA' SHOULD NOT BE REPLACED.

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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
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